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CHEMICAL MECHANICAL POLISHING
INVENTOR: YUFEI CHEN, ET AL.
EXPRESS MAIL NO.: EV335470135US

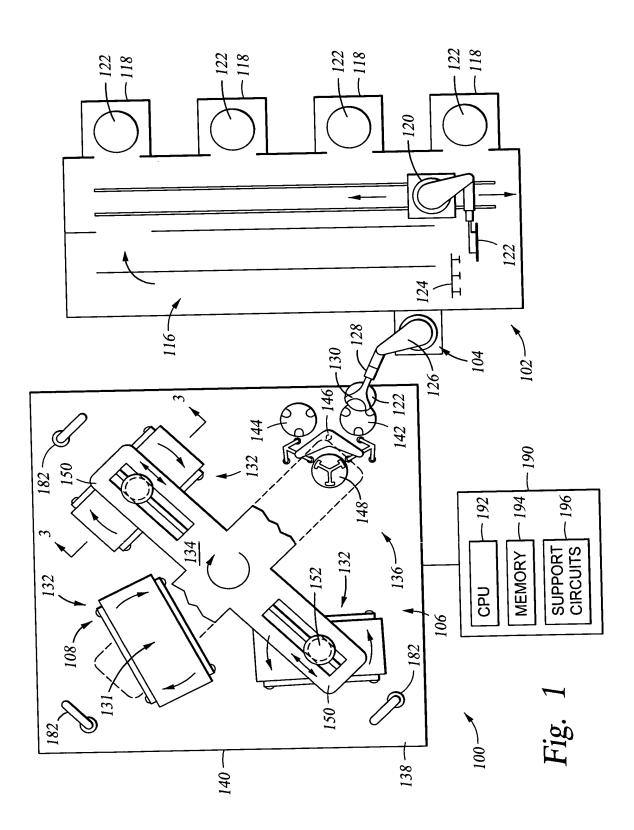
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PAGE 2 OF 3

2/3

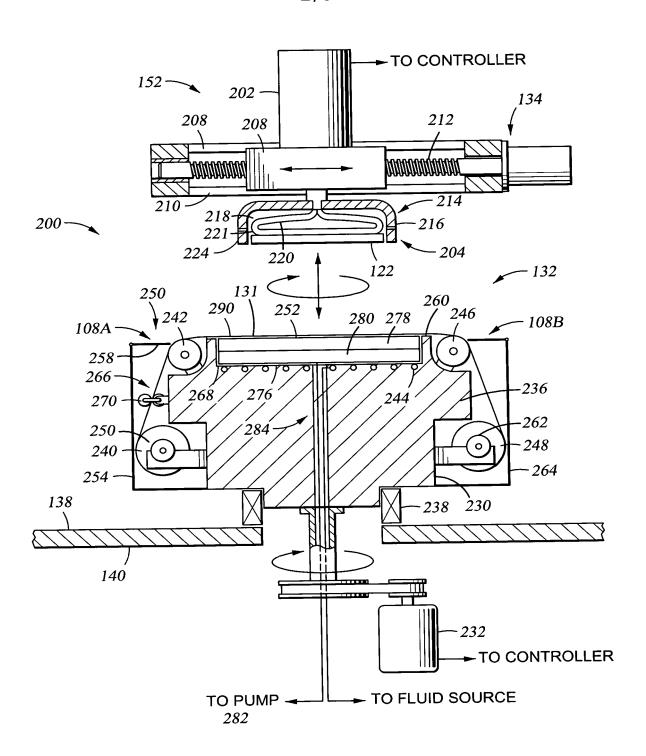


Fig. 2

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3/3

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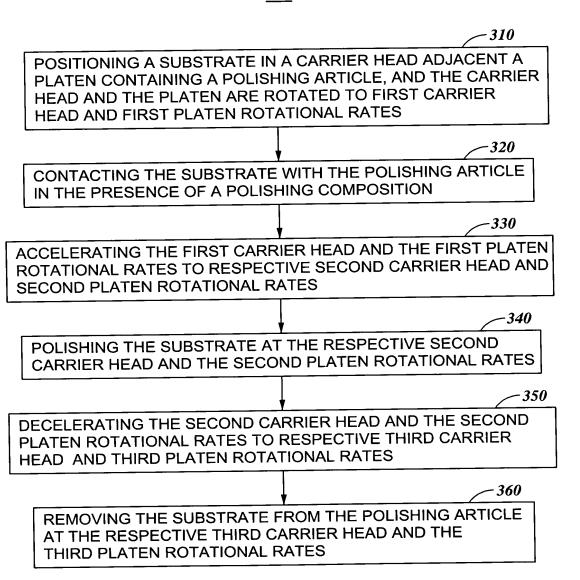


Fig. 3